PATENT
Attorney Docket No.: COOL-01301

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Group Art Unit: 3753
Thomas W. Kenny et al.	Examiner:
Serial No.: 10/680,584	**TRANSMITTAL LETTER**
Filed: October 6, 2003	162 N. Wolfe Road Sunnyvale, CA 94086 (408) 530-9700
For: **METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE**	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #59961); (EFS ID #59962); (EFS ID #59963) and (EFS ID #59964) filed on April 28, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

By: Thomas B. Haverstock
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CERTIFICATE OF MAILING (37 CFR§ 1.8(a))

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HAVERSTOCK & OWENS LLP.

Date: 4/29/04 By:

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #59961); (EFS ID #59962); (EFS ID #59963) and (EFS ID #59964). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
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This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

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FORM PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney Docket No.: COOL-01301	Serial No.: 10/680,584
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)		Applicants: Thomas W. Kenny et al.	
(37 CFR § 1.98(b))		Filing Date: October 6, 2003	Group Art Unit: 3753

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Examiner:	Date Considered:

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(37 CFR § 1.98(b))		Filing Date: October 6, 2003	Group Art Unit: 3753

		OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)
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Electronic Version 1.1
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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Submission Type: Information Disclosure Statement

Application Number: 10/680584 *10/680584*

EFS ID: 59961

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ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.

First Named Applicant: Thomas Kenny

Attorney Docket Number:

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Date: 2003-10-06
First Named Applicant: Thomas W. Kenny

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Confirmation Number: 5276
First Named Applicant: Thomas Kenny
Attorney Docket Number:
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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Submission Type: Information Disclosure Statement

Application Number: 10/680584 *10/680584*

EFS ID: 59962

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
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First Named Applicant: Thomas W. Kenny

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Application Number: 10/680584 *10/680584*
Confirmation Number: 5276
First Named Applicant: Thomas Kenny
Attorney Docket Number:
Search string: (5383340 or 5421943 or 5427174 or 5436793 or 5459099 or 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618 or 5759014 or 5763951 or 5774779 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5869004 or 5870823 or 5874795 or 5876655 or 5880017 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164 or 6019882 or 6054034 or 6068752).pn.

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	46	6010316	2000-01-04	Haller et al.
	47	6013164	2000-01-11	Paul et al.
	48	6019882	2000-02-01	Paul et al.
	49	6054034	2000-04-25	Soane et al.
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Electronic Version 1.1
Stylesheet Version v1.1.1

Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Submission Type: Information Disclosure Statement

Application Number: 10/680584 *10/680584*

EFS ID: 59964

Server Response:

Confirmation Code	Message
ISVR1	Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application
ICON1	5276
ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Timestamp: 2004-04-28 13:31:53 EDT

From: us

File Listing:

Doc. Name	File Name	Size (Bytes)
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us-ids	us-ids.dtd	7763

us-ids	us-ids.xsl	12026
package-data	COOL01301D-pkda.xml	1773
package-data	package-data.dtd	27025
package-data	us-package-data.xsl	19263
	Total files size	70338

Message Digest: e11925862dea3d91c6b73869094d085a219df54f

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Date: 2003-10-06
First Named Applicant: Thomas W. Kenny

Confirmation Number: 5276
Attorney Docket Number:

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Submitted by:	Elec. Sign.	Sign. Capacity
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney

Documents being submitted	Files
us-ids	COOL01301D-usidst.xml us-ids.dtd us-ids.xsl

Comments

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Electronic Version v1 8
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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Confirmation Number: 5276
First Named Applicant: Thomas Kenny
Attorney Docket Number:
Search string: (6632655 or 20010016985 or 20010024820 or 20010044155 or 20010045270 or 20010046703 or 20010055714 or 20020011330 or 20020134543).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6632655	2003-10-14	Mehta et al.	B1		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

Init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010016985	2001-08-30	Insley et al.	A1		
	2	20010024820	2001-09-27	Mastromatteo et al.	A1		
	3	20010044155	2001-11-22	Paul et al.	A1		
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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Submission Type: Information Disclosure Statement

Application Number: 10/680584 *10/680584*

EFS ID: 59963

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ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.

First Named Applicant: Thomas Kenny

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File Listing:

Doc. Name	File Name	Size (Bytes)
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package-data	us-package-data.xsl	19263
	Total files size	77411

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Date: 2003-10-06
First Named Applicant: Thomas W. Kenny

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Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney

Documents being submitted	Files
us-ids	COOL01301C-usidst.xml us-ids.dtd us-ids.xsl

Comments

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	METHOD AND APPARATUS FOR EFFICIENT VERTICAL FLUID DELIVERY FOR COOLING A HEAT PRODUCING DEVICE

Application Number: 10/680584 *10/680584*
Confirmation Number: 5276
First Named Applicant: Thomas Kenny
Attorney Docket Number:
Search string: (6090251 or 6096656 or 6100541 or 6101715 or 6119729 or 6126723 or 6129145 or 6129260 or 6131650 or 6146103 or 6154363 or 6159353 or 6171067 or 6174675 or 6176962 or 6186660 or 6210986 or 6216343 or 6221226 or 6227809 or 6234240 or 6238538 or 6277257 or 6287440 or 6301109 or 6313992 or 6317326 or 6321791 or 6322753 or 6324058 or 6337794 or 6351384 or 6388317 or 6396706 or 6400012 or 6406605 or 6415860 or 6416642 or 6417060 or 6424531 or 6443222 or 6444461 or 6457515 or 6495015 or 6537437 or 6543521 or 6553253 or 6572749 or 6588498 or 6591625).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6096656	2000-08-01	Matzke et al.			
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	50	6591625	2003-07-15	Simon	B1

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Examiner Name	Date